

Description

The AO4410-HXY uses advanced trench technology to provide excellent $R_{DS(ON)}$, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

General Features

$$\begin{split} V_{DS} &= 30V \ I_{D} = 15 \ A \\ R_{DS(ON)} &< 6.5 m \Omega \quad @ \ V_{GS} = 10V \\ R_{DS(ON)} &< 12 m \Omega \quad @ \ V_{GS} = 4.5V \end{split}$$

Application

Battery protection

Load switch

Uninterruptible power supply

Package Marking and Ordering Information

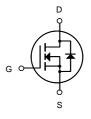
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Product ID	Pack	Marking	Qty(PCS)
AO4410-HXY	SOP-8	4410 XXX YYYY	3000

Absolute Maximum Ratings (Tc=25°C unless otherwise noted)

Symbol	Parameter	Limit	Unit
VDS	Drain-Source Voltage	30	V
Vgs	Gate-Source Voltage	±20	V
I _D	Drain Current-Continuous	15.0	А
l₀(70 °C)	Drain Current-Continuous(Tc=70℃)	8.2	А
Ы	Pulsed Drain Current	42	A
PD	Maximum Power Dissipation	1.5	W
Eas	Single pulse avalanche energy (Note 5)	62	mJ
Tj,Tstg	Operating Junction and Storage Temperature Range	-55 To 150	°C
Rejc	Thermal Resistance, Junction-to-Case ^(Note 2)	36	°C /W



SOP-8



N-Channel MOSFET



Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	ymbol Parameter Conditions		Min.	Тур.	Max.	Unit	
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	30			V	
$\triangle BV_{\text{DSS}} / \triangle T_{\text{J}}$	BVDSS Temperature Coefficient	Reference to 25° C , I _D =1mA		0.027		V/°C	
Rds(ON)	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =10A		7.5	9	mΩ	
		V _{GS} =4.5V , I _D =8A		11	14		
$V_{GS(th)}$	Gate Threshold Voltage	−V _{GS} =V _{DS} , I _D =250uA	1.2	1.5	2.5	V	
$ riangle V_{GS(th)}$	GS(th) Temperature Coefficient			-5.8		mV/°C	
		V _{DS} =24V , V _{GS} =0V , T _J =25°C			1		
IDSS	Drain-Source Leakage Current	V _{DS} =24V , V _{GS} =0V , T _J =55°C			5	uA	
lgss	Gate-Source Leakage Current	V _{GS=} ±20V , V _{DS} =0V			±100	nA	
gfs	Forward Transconductance	V _{DS} =5V , I _D =10A		5.8		S	
Rg	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.2	3.8	Ω	
Qg	Total Gate Charge (4.5V)			12.6	17.6		
Qgs	Gate-Source Charge	V _{DS} =15V , V _{GS} =4.5V , I _D =10A		4.2	5.9	nC	
Q_{gd}	Gate-Drain Charge			5.1	7.1		
T _{d(on)}	Turn-On Delay Time			6.2	12.4		
Tr	Rise Time	V_{DD} =15V , V_{GS} =10V , R_{G} =3.3 Ω		59	106		
$T_{d(off)}$	Turn-Off Delay Time	ID=10A		27.6	55	ns -	
T _f	Fall Time			8.4	16.8		
Ciss	Input Capacitance			1317	1845		
Coss	Output Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		163	228.2	pF	
Crss	Reverse Transfer Capacitance			131	183.4		

Diode Characteristics

Symbol	Parameter	Conditions Min		Тур.	Max.	Unit
ls	Continuous Source Current ^{1,5}	$\frac{1}{2}$			10.3	А
I _{SM}	Pulsed Source Current ^{2,5}	V _G =V _D =0V , Force Current			42	А
Vsd	Diode Forward Voltage ²	V _{GS} =0V , I _S =1A , T _J =25°C			1.2	V
t _{rr}	Reverse Recovery Time			12.5		nS
Qrr	Reverse Recovery Charge	IF=10A,dI/dt=100A/µs,Tյ=25℃		5		nC

Note :

1. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.

2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%

3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =35A

4. The power dissipation is limited by 150°C junction temperature

5. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



Typical Characteristics

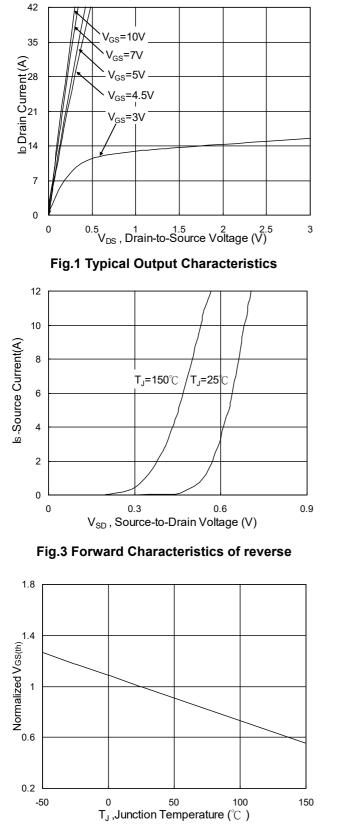


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

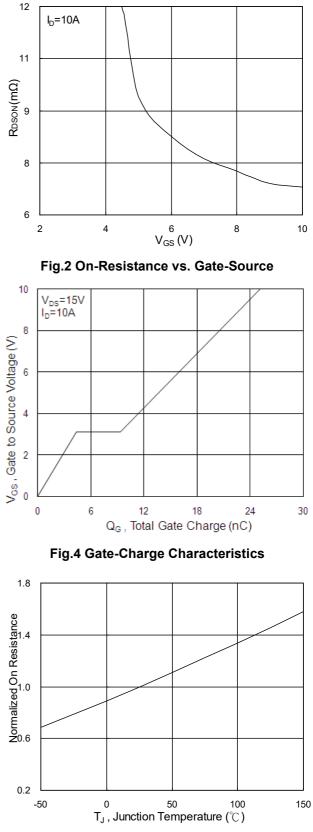


Fig.6 Normalized R_{DSON} vs. T_J



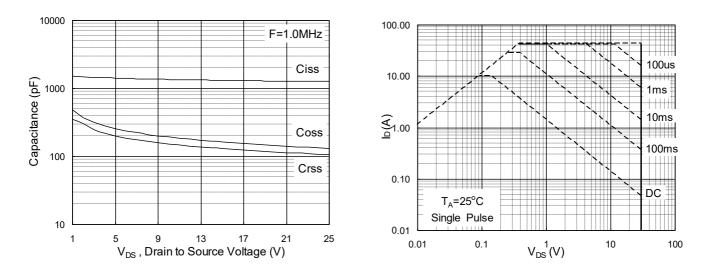
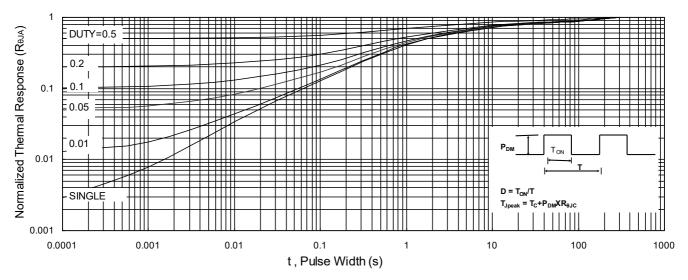


Fig.7 Capacitance

Fig.8 Safe Operating Area





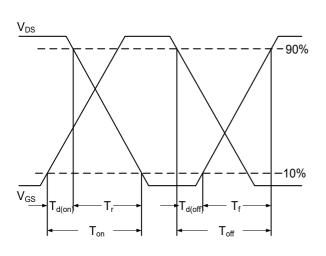


Fig.10 Switching Time Waveform

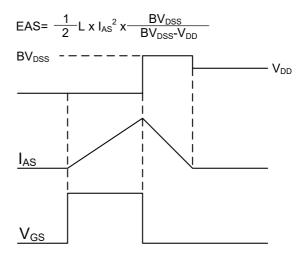
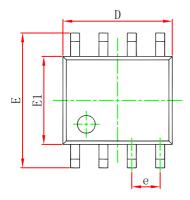
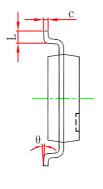


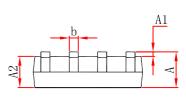
Fig.11 Unclamped Inductive Switching Waveform



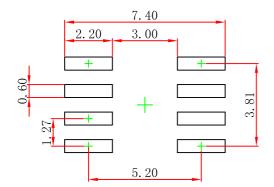
SOP-8 Package Outline Dimensions







Symbol	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min	Max	Min	Max	
Α	1.350	1.750	0.053	0.069	
A1	0.100	0.250	0.004	0.010	
A2	1.350	1.550	0.053	0.061	
b	0.330	0.510	0.013	0.020	
с	0.170	0.250	0.007	0.010	
D	4.800	5.000	0.189	0.197	
e	1.270 (BSC)		0.050 (BSC)		
E	5.800	6.200	0.228	0.244	
E1	3.800	4.000	0.150	0.157	
L	0.400	1.270	0.016	0.050	
θ	0 °	8°	0 °	8°	



Note: 1.Controlling dimension: in millimeters.

2.General tolerance:± 0.05mm.
 3.The pad layout is for reference purposes only.



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